Multimedia Available: Applied Materials Transcends the Boundaries of Traditional Wafer Inspection with New ComPlus-EV

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--(BUSINESS WIRE)--

Applied Materials Inc. breaks through the barriers of traditional wafer inspection technology with its innovative ComPlus(tm)-EV, the industry's only system that performs high-speed wafer inspection for all darkfield and key brightfield applications for 90nm production. Using proprietary Enlarged GrayField(tm) technology, this single-system solution captures up to 50 percent more defects than the previous system at speeds of up to 60 wafers per hour, enabling faster ramps and higher production yields.

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